#### JP2002184765

# **CLEANING GAS**

### CENTRAL GLASS CO LTD

Inventor(s): ;MORI ISAMU ;OHASHI MITSUYA ;KAWASHIMA TADAYUKI ;TAMURA TETSUYA ;TANAKA KENJI ;TODA MAKOTO

**Application No.** 2000384111, Filed 20001218, Published 20020628

### Abstract:

PROBLEM TO BE SOLVED: To provide a cleaning gas for eliminating unwanted deposits deposited on the inner wall of a thin film formation equipment or the like and in jigs, components, pipings, or the like of the equipment.

SOLUTION: The cleaning gas consists of a COF2 gas mixed with a CF2(OF)2, CF3OF, CF3OOCF3, or F2 gas.

Int'l Class: H01L0213065 C23C01400 C23C01644 C23F00400 H01L021205

MicroPatent Reference Number: 002331853

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### JP2000038675

### **CLEANING GAS**

# CENTRAL GLASS CO LTD

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**Application No.** 10206708, Filed 19980722, Published 20000208

# Abstract:

PROBLEM TO BE SOLVED: To rapidly clean with high cleanness and without problem of causing global warming by using a gas containing CF3OOCF3 in order to remove unnecessary deposits accumulated in a device for forming thin films.

SOLUTION: The unnecessary deposits accumulated in the apparatus for forming thin films are removed by using a cleaning gas containing a gas comprising CF3OOCF3 or CF3OOCF3 and a gaseous halogen or a gaseous halogenated compound. The cleaning gas can be used for cleaning reaction chamber walls, pipings and a substrate- transporting room of the apparatus for depositing B, P, W, Si, Ti, V, Nb, Ta, Se, Te, Mo, Re, Os, Ir, Sb, Ge, Au, Ag, As, Cr and compounds thereof, concretely, oxides, nitrides and carbides,

and alloys thereof. This cleaning gas exhibits high etching rate in terms of supplied molecular weight and can be easily decomposed by using a dry-type device for removing toxicity with warmed Si as a reagent for removing toxicity.

Int'l Class: C23C01644 C11D00702 C11D00728 C11D01700 C23C01400 H01L021205

H01L0213065

MicroPatent Reference Number: 001379693

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